

# **TL3116CDR Datasheet**



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DiGi Electronics Part Number TL3116CDR-DG

Manufacturer Texas Instruments

Manufacturer Product Number TL3116CDR

Description IC COMPARATOR 1 GEN PUR 8SOIC

**Detailed Description** Comparator General Purpose Complementary, Pus

h-Pull, TTL 8-SOIC



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# **Purchase and inquiry**

facturer:						
Instruments						
ict Status:						
ete						
per of Elements:						
ge - Supply, Single/Dual (±):						
0V, ±2.5V ~ 5V						
nt - Input Bias (Max):						
1.1μA @ ±5V						
nt - Quiescent (Max):						
nA						
ngation Delay (Max):						
ating Temperature:						
70°C						
ting Type:						
ce Mount						
Product Number:						
6						

# **Environmental & Export classification**

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	

8542.39.0001

# TL3116, TL3116Y **ULTRA-FAST LOW-POWER** PRECISION COMPARATO

SLCS132C - MARCH 1997 - REVISED MAY 1997

- Ultra-Fast Operation . . . 10 ns (typ)
- **Low Positive Supply Current** 12.7 mA (Typ)
- Operates From a Single 5-V Supply or From a Split ±5-V Supply
- **Complementary Outputs**
- Input Common-Mode Voltage Includes **Negative Rail**
- **Low Offset Voltage**
- No Minimum Slew Rate Requirement
- **Output Latch Capability**
- **Functional Replacement to the LT1116**

# description

The TL3116 is an ultra-fast comparator designed to interface directly to TTL logic while operating from either a single 5-V power supply or dual ±5-V supplies. The input common-mode voltage extends to the negative rail for ground sensing applications. It features extremely tight offset voltage and high gain for precision applications. It has complementary outputs that can be latched using the LATCH ENABLE terminal. Figure 1 shows the positive supply current of the comparator. The TL3116 only requires 12.7 mA (typical) to achieve a propagation delay of 10 ns.

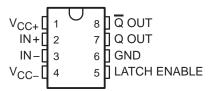
The TL3116 is a pin-for-pin functional replacement for the LT1116 comparator, offering high-speed operation but consuming much less power.

#### **AVAILABLE OPTIONS**

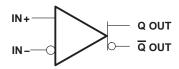
	PACKAGED	0.115	
TA	SMALL OUTLINE† (D)	TSSOP (PW)	CHIP FORM <sup>‡</sup> (Y)
0°C to 70°C	TL3116CD	TL3116CPWLE	TL3116Y
-40°C to 85°C	TL3116ID	TL3116IPWLE	_

†The PW packages are available left-ended taped and reeled only.

#### D AND PW PACKAGE (TOP VIEW)

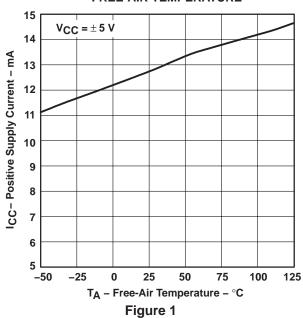


### symbol (each comparator)



# **POSITIVE SUPPLY CURRENT**

# FREE-AIR TEMPERATURE





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



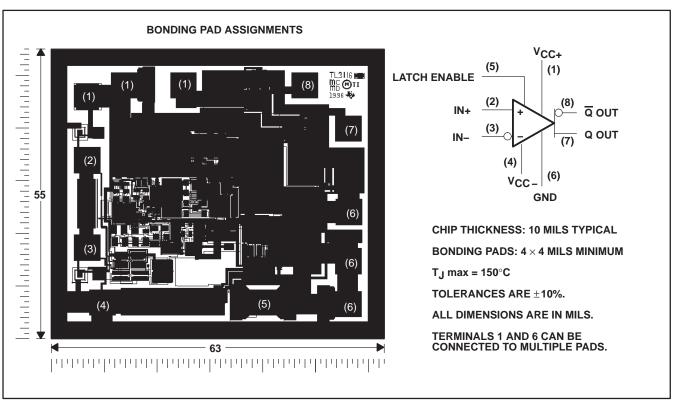
<sup>‡</sup> Chip forms are tested at  $T_A = 25^{\circ}C$  only.

# TL3116, TL3116Y ULTRA-FAST LOW-POWER PRECISION COMPARATORS

SLCS132C - MARCH 1997 - REVISED MAY 1997

# **TL3116Y chip information**

This chip, when properly assembled, displays characteristics similar to the TL3116C. Thermal compression or ultrasonic bonding may be used on the doped-aluminum bonding pads. Chips may be mounted with conductive epoxy or a gold-silicon preform.



COMPONENT COUNT									
Bipolars	53								
MOSFETs	49								
Resistors	46								
Capacitors	14								



# TL3116, TL3116Y ULTRA-FAST LOW-POWER PRECISION COMPARATORS SLCS132C - MARCH 1997 - REVISED MAY 1997

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>DD</sub> (see Note 1)	– 7 V to 7 V
Differential input voltage, V <sub>ID</sub> (see Note 2)	7 V
Input voltage range, V <sub>I</sub>	7 V
Input voltage, V <sub>I</sub> (LATCH ENABLE)	7 V
Output current, I <sub>O</sub>	$\dots \dots \pm 20 \text{ mA}$
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T <sub>A</sub>	–40°C to 85°C
Storage temperature range, T <sub>sta</sub>	– 65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential voltages, are with respect to network ground.

2. Differential voltages are at IN+ with respect to IN-.

#### **DISSIPATION RATING TABLE**

PACKAGE	T <sub>A</sub> ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING			
D	725 mW	5.8 mW/°C	464 mW			
PW	525 mW	4.2 mW/°C	336 mW			



# TL3116, TL3116Y ULTRA-FAST LOW-POWER PRECISION COMPARATORS

SLCS132C - MARCH 1997 - REVISED MAY 1997

# electrical characteristics at specified operating free-air temperature, $V_{DD}$ = $\pm 5$ V, $V_{LE}$ = 0 (unless otherwise noted)

PARAMETER				TL31160	;				
		TEST CONDITIONS†	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
\/	lanut offeet voltage	T <sub>A</sub> = 25°C		0.5	3		0.5	3	mV
VIO	Input offset voltage	T <sub>A</sub> = full range			3.5			3.5	mv
ανιο	Temperature coefficient of input offset voltage			-2.5			-2.8		μV/°C
	land offert comment	T <sub>A</sub> = 25°C		0.1	0.2		0.1	0.2	
liO	Input offset current	T <sub>A</sub> = full range			0.3			0.35	μΑ
1	lanut biog gurrant	T <sub>A</sub> = 25°C		0.7	1.1		0.7	1.1	^
IВ	Input bias current	T <sub>A</sub> = full range			1.2			1.5	μΑ
1/	Common-mode input	$V_{DD} = \pm 5 \text{ V}$	-5		2.5	-5		2.5	V
VICR	voltage range	V <sub>DD</sub> = 5 V	0		2.5	0		2.5	V
CMRR	Common-mode rejection ratio	-5 ≤ V <sub>IC</sub> ≤ 2.5 V	75	100		75	100		dB
Sı	Supply-voltage rejection ratio	Positive supply: 4.6 V $\leq$ +V <sub>DD</sub> $\leq$ 5.4 V T <sub>A</sub> = 25°C	60	80		60	80		
ksvr		Negative supply: $-7 \text{ V} \le -V_{DD} \le -2 \text{ V}$ T <sub>A</sub> = 25°C	, 80	100		80	100		dB
,,		$I_{(sink)} = 4 \text{ mA},$ $V+ \le 4.6 \text{ V},$ $T_A = 25^{\circ}\text{C}$		400	600		400	600	.,
VOL	Low-level output voltage	$I_{(sink)} = 10 \text{ mA}, V+ \le 4.6 \text{ V},$ $T_A = 25^{\circ}\text{C}$		750			750		mV
	LPak land autout value	$V+ \le 4.6 \text{ V},$ $I_O = 1 \text{ mA},$ $T_A = 25^{\circ}\text{C}$	3.6	3.9		3.6	3.9		V
VOH	High-level output voltage	$V+ \leq 4.6 \text{ V}, \\ T_{\mbox{\scriptsize A}} = 25^{\circ}\mbox{\scriptsize C}$	3.4	3.8		3.4	3.8		V
	Positive supply current	T. College or		12.7	14.7		12.7	15	0
ICC	Negative supply current	T <sub>A</sub> = full range	-2.6			-3			mA
VIL	Low-level input voltage (LATCH ENABLE)				0.8			0.8	V
VIH	High-level input voltage (LATCH ENABLE)		2			2			V
	Low-level input current	V <sub>LE</sub> = 0		0	1		0	1	μΑ
II∟	(LATCH ENABLE)	V <sub>LE</sub> = 2 V		24	39		24	45	μΑ
L	an for the TLOMACC in T		_	00 to 0500					

<sup>†</sup> Full range for the TL3116C is  $T_A = 0^{\circ}$ C to  $70^{\circ}$ C. Full range for the TL3116I is  $T_A = -40^{\circ}$ C to  $85^{\circ}$ C. ‡ All typical values are measures with  $T_A = 25^{\circ}$ C.



# switching characteristics, $V_{\mbox{\scriptsize DD}}$ = $\pm 5$ V, $V_{\mbox{\scriptsize LE}}$ = 0

PARAMETER		TEOT 001	TL3116C			TL3116I			LINUT	
	PARAMETER	TEST CON	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
		$\Delta V_{I} = 100 \text{ mV},$	T <sub>A</sub> = 25°C		9.9	12		9.9	12	
	Propagation delay time‡	$V_{OD} = 5 \text{ mV}$	T <sub>A</sub> = full range		9.9	14		9.9	15	
<sup>t</sup> pd1		$\Delta V_I = 100 \text{ mV},$ $V_{OD} = 20 \text{ mV}$	T <sub>A</sub> = 25°C		8.2	10.3		8.2	10.3	ns
			T <sub>A</sub> = full range		8.2	12.7		8.2	13.7	
t <sub>sk(p)</sub>	Pulse skew ( t <sub>pd+</sub> - t <sub>pd-</sub>  )	$\Delta V_I = 100 \text{ mV},$ $T_A = 25^{\circ}\text{C}$	$V_{OD} = 5 \text{ mV},$		0.5			0.5		ns
t <sub>su</sub>	Setup time, LATCH ENABLE				3.4			3.4		ns

Full range for the TL3116C is 0°C to 70°C. Full range for the TL3116I is –40°C to 85°C.

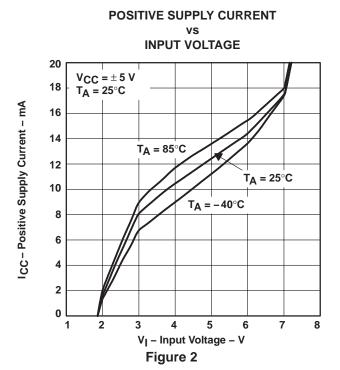
# **TYPICAL CHARACTERISTICS**

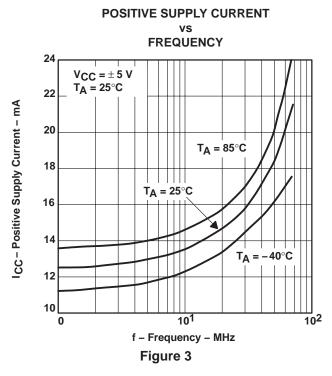
# **Table of Graphs**

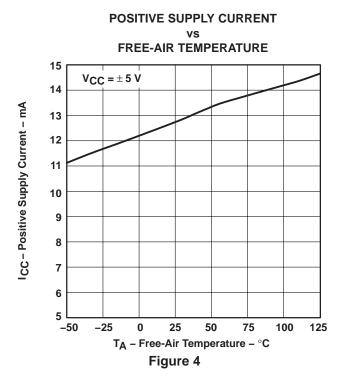
			FIGURE
		vs Input voltage	2
ICC	Positive supply current	vs Frequency	3
		vs Free-air temperature	4
ICC	Negative supply current	vs Free-air temperature	5
		vs Overdrive voltage	6
		vs Supply voltage	7
tpd	Propagation delay time	vs Input impedance	8
·		vs Load capacitance	9
		vs Free-air temperature	10
V <sub>IC</sub>	Common-mode input voltage	vs Free-air temperature	11
$V_{IT}$	Input threshold voltage (LATCH ENABLE)	vs Free-air temperature	12
.,		vs Output source current	13
VO	Output voltage	vs Output sink current	14
IĮ	Input current (LATCH ENABLE)	vs Input voltage	15

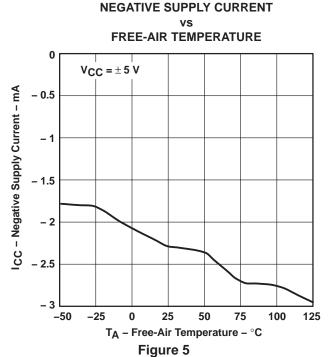
<sup>‡</sup> t<sub>pd1</sub> cannot be measured in automatic handling equipment with low values of overdrive. The TL3116 is 100% tested with a 1-V step and 500-mV overdrive at T<sub>A</sub> = 25°C only. Correlation tests have shown that t<sub>pd1</sub> limits given can be ensured with this test, if additional dc tests are performed to ensure that all internal bias conditions are correct. For low overdrive conditions, V<sub>OS</sub> is added to the overdrive.

# TYPICAL CHARACTERISTICS

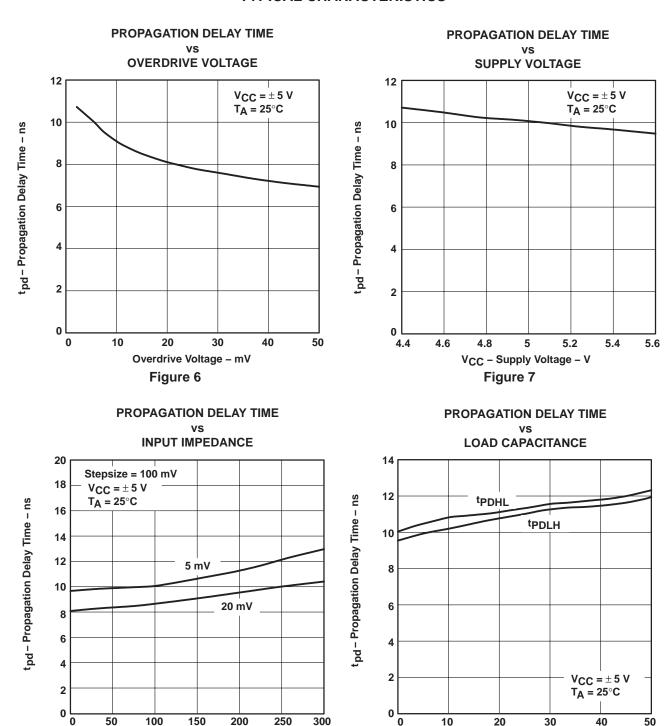








#### **TYPICAL CHARACTERISTICS**





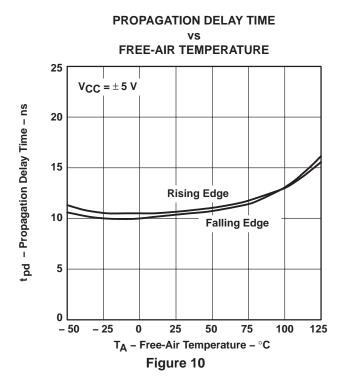
 $Z_I$  - Input Impedance -  $\Omega$ 

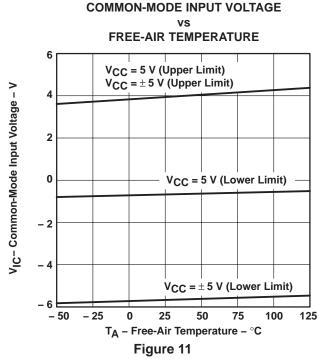
Figure 8

C<sub>L</sub> - Load Capacitance - pF

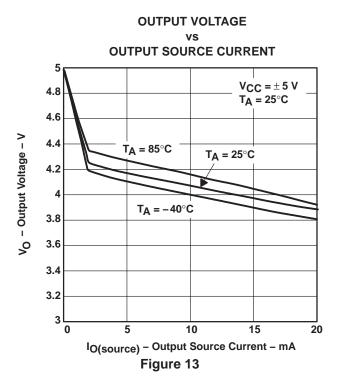
Figure 9

#### TYPICAL CHARACTERISTICS

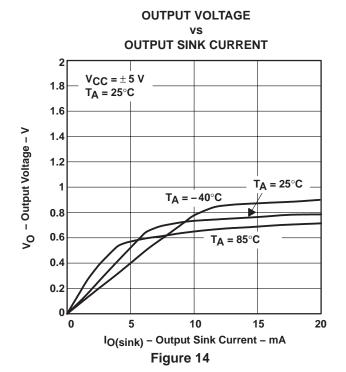


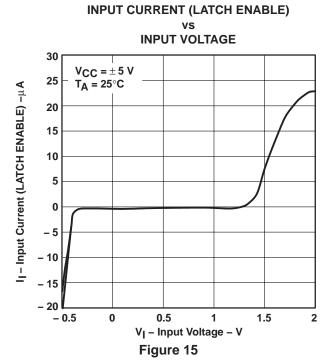


# INPUT THRESHOLD VOLTAGE (LATCH ENABLE) vs FREE-AIR TEMPERATURE V<sub>Π</sub> - Input Threshold Voltage (LATCH ENABLE) - V 2 $V_{CC} = \pm 5 V$ 1.8 1.6 1.4 1.2 8.0 0.6 0.4 0.2 -50 -25 25 50 75 100 125 $T_A$ – Free-Air Temperature – $^{\circ}C$ Figure 12



# **TYPICAL CHARACTERISTICS**







# PACKAGE OPTION ADDENDUM

18-Sep-2024 www.ti.com

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
TL3116CD	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	0 to 70	3116C	
TL3116CDR	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	0 to 70	3116C	
TL3116CPWR	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI	0 to 70	T3116	
TL3116ID	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-40 to 85	31161	
TL3116IDR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	3116I	Samples
TL3116IPWR	ACTIVE	TSSOP	PW	8	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3116	Samples

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

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Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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# TL3116CDR Texas Instruments IC COMPARATOR 1 GEN PUR 8SOIC

# PACKAGE OPTION ADDENDUM

TEXAS INSTRUMENTS

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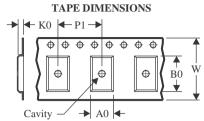


# **PACKAGE MATERIALS INFORMATION**

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# TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



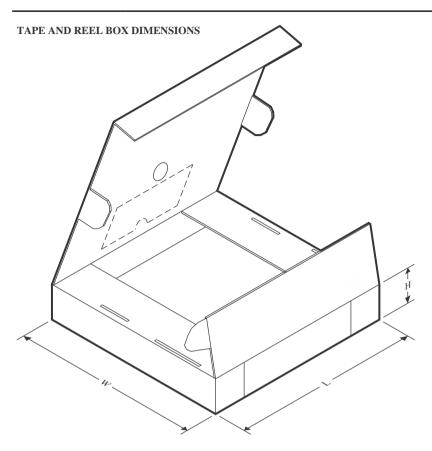
#### \*All dimensions are nominal

	Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TI	L3116IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL	3116IPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1



# **PACKAGE MATERIALS INFORMATION**

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#### \*All dimensions are nominal

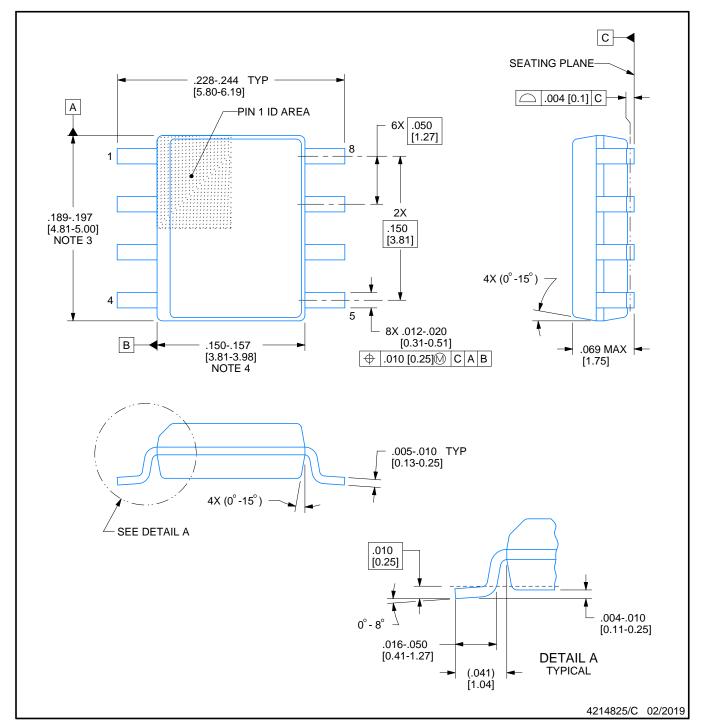
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL3116IDR	SOIC	D	8	2500	350.0	350.0	43.0
TL3116IPWR	TSSOP	PW	8	2000	356.0	356.0	35.0



# **PACKAGE OUTLINE**

# SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



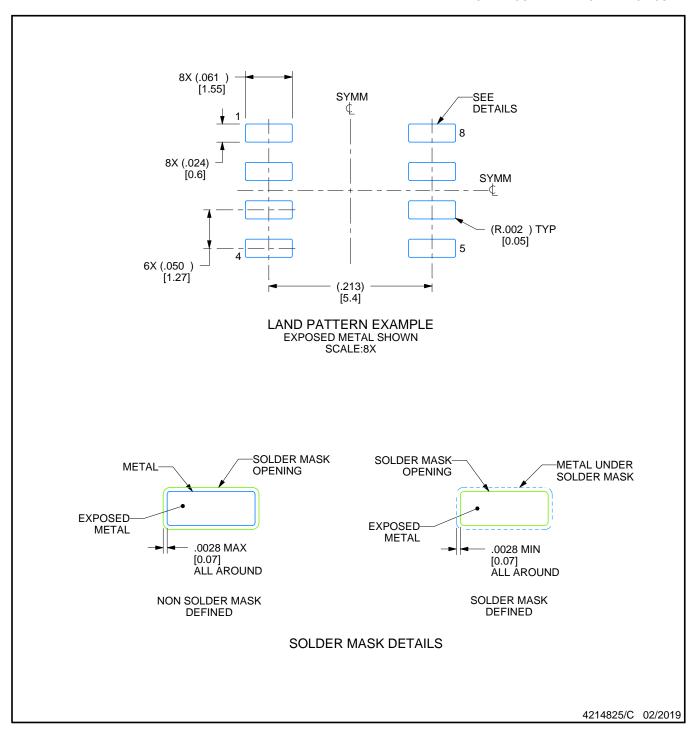
### NOTES:

**D0008A** 

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



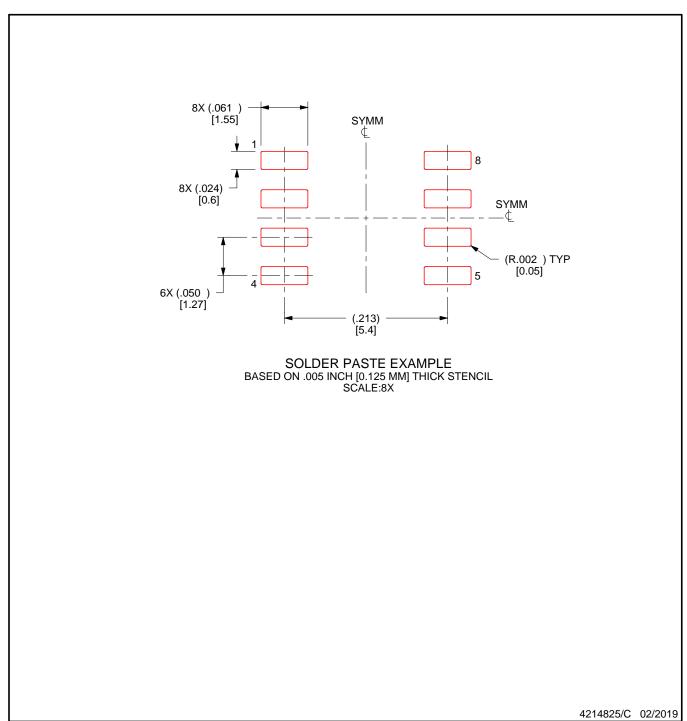
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



#### NOTES: (continued)

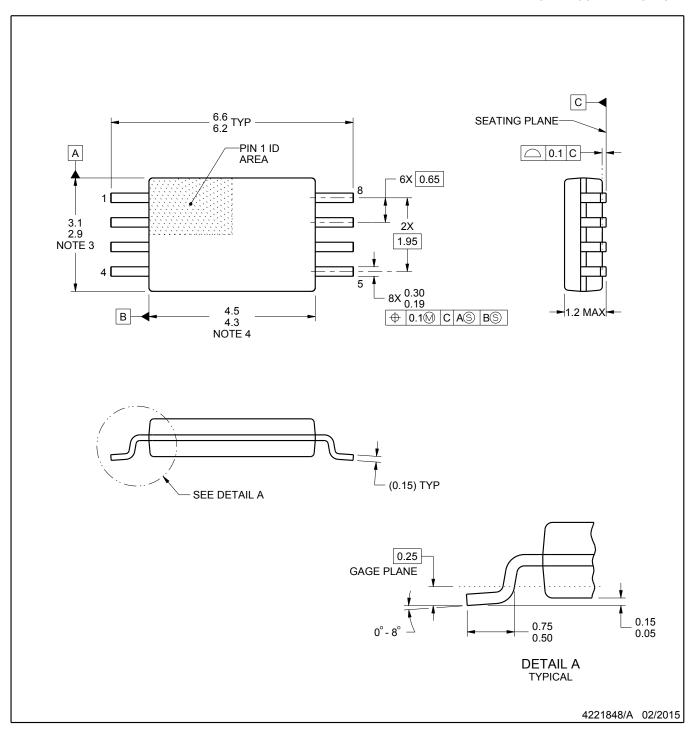
- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.





# TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



#### NOTES:

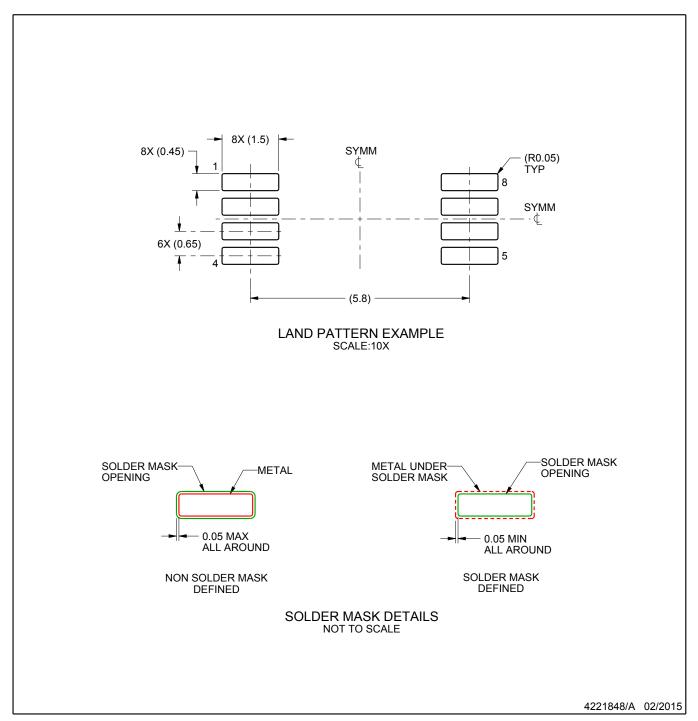
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153, variation AA.



SMALL OUTLINE PACKAGE



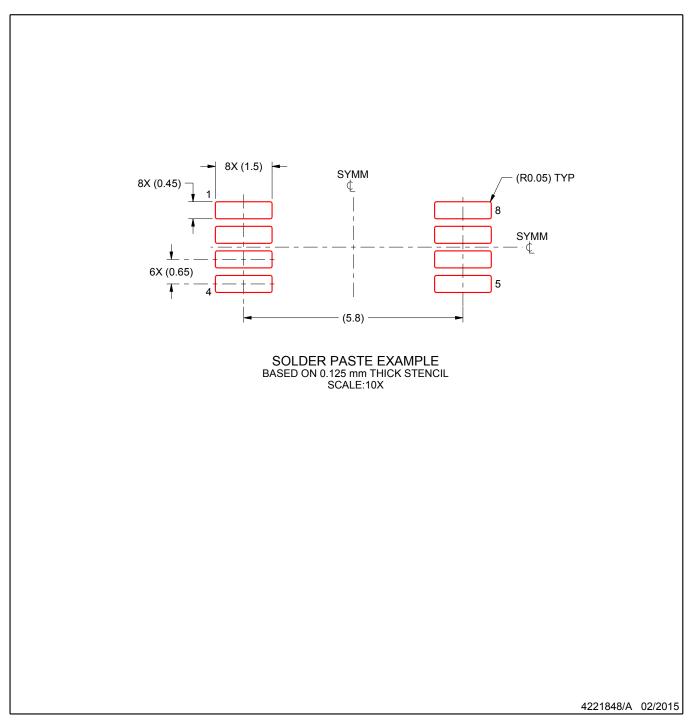
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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